

**AMENDMENTS TO THE CLAIMS**

1. (currently amended) A method of connecting an electronic part, comprising:  
forming an electroless nickel plating coat containing phosphorous on a pad having a size of 300  $\mu\text{m}$  or less in diameter and comprising Ni crystals that have a half-width of X-ray diffraction of a (111) plane in a range of 4 degrees to 2 degrees, on a substrate metal layer which constitutes a connecting terminal of an electronic part; and  
carrying out binding connecting to the nickel plating coat through a lead-free solder;  
~~wherein a half-width of X-ray diffraction of a (111) plane of Ni crystal in the nickel plating coat is 5 degrees or less.~~
2. (original) The connecting method according to Claim 1, wherein the plating coat is formed using an electroless nickel plating solution containing 5.5 mass% or less of phosphorous.
3. (original) The connecting method according to Claim 1, wherein the plating coat is formed using an electroless nickel plating solution containing 4.5 mass% or less of phosphorous.
4. (cancelled).
5. (cancelled).
6. (original) The connecting method according to Claim 1, wherein annealing is carried out at a temperature of 250°C to 400°C, after the electroless nickel plating coat is formed.